



# SOT1709-1

SO8, plastic, small outline package; 8 terminals; 1.27 mm pitch; 7.36 mm x 7.36 mm x 4.19 mm body

17 September 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	SO8
<b>Package type industry code</b>	SO8
<b>Package style descriptive code</b>	SO (small outline)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	01-02-2016
<b>Manufacturer package code</b>	98ARH99066A

**Table 1. Package summary**

Parameter	Min	Nom	Max	Unit
package length	-	7.36	-	mm
package width	-	7.36	-	mm
package height	-	4.19	-	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	8	-	



SO8, plastic, small outline package; 8 terminals; 1.27 mm pitch; 7.36 mm x 7.36 mm x 4.19 mm body

2 Package outline

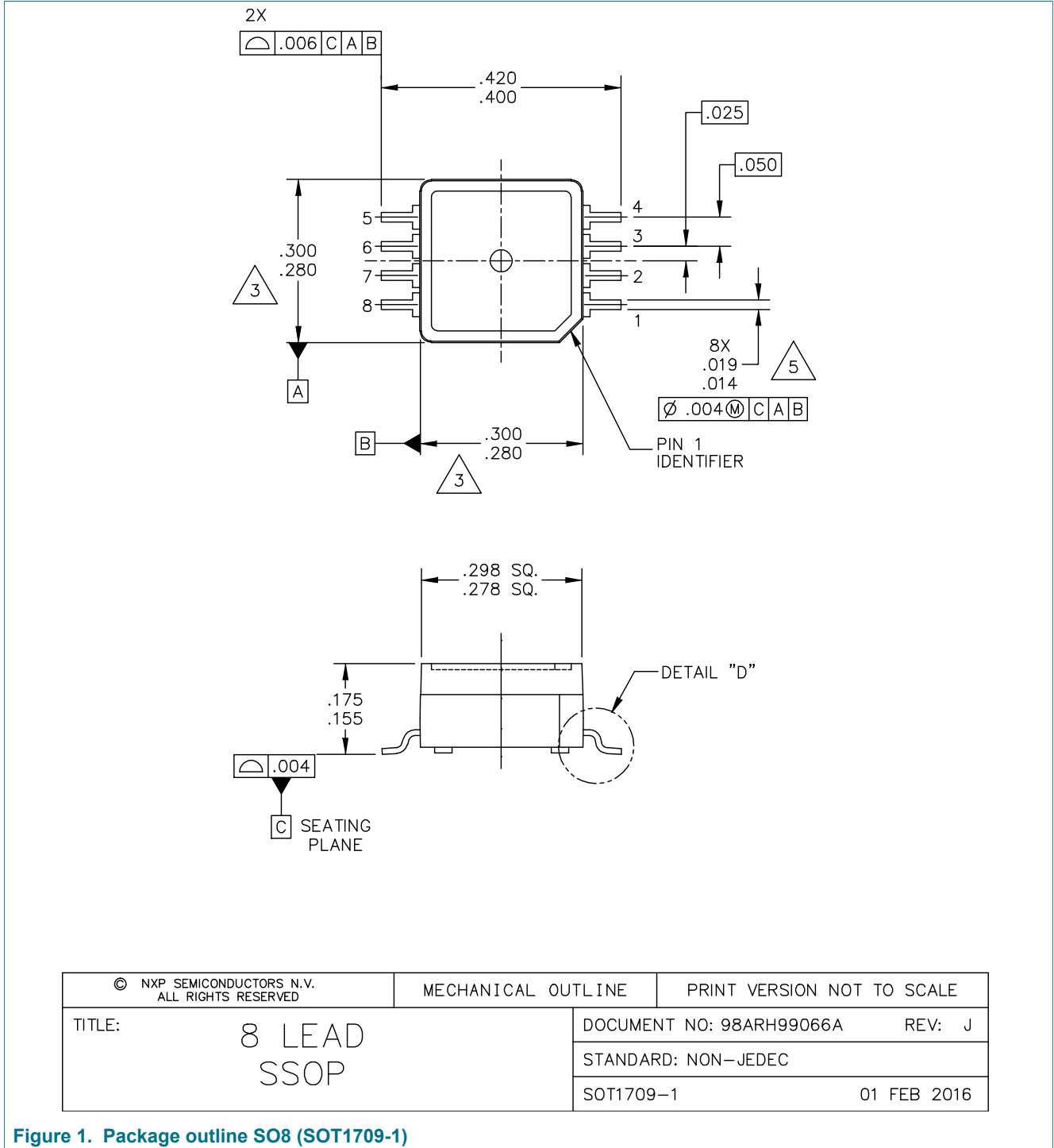


Figure 1. Package outline SO8 (SOT1709-1)

SO8, plastic, small outline package; 8 terminals; 1.27 mm pitch; 7.36 mm x 7.36 mm x 4.19 mm body

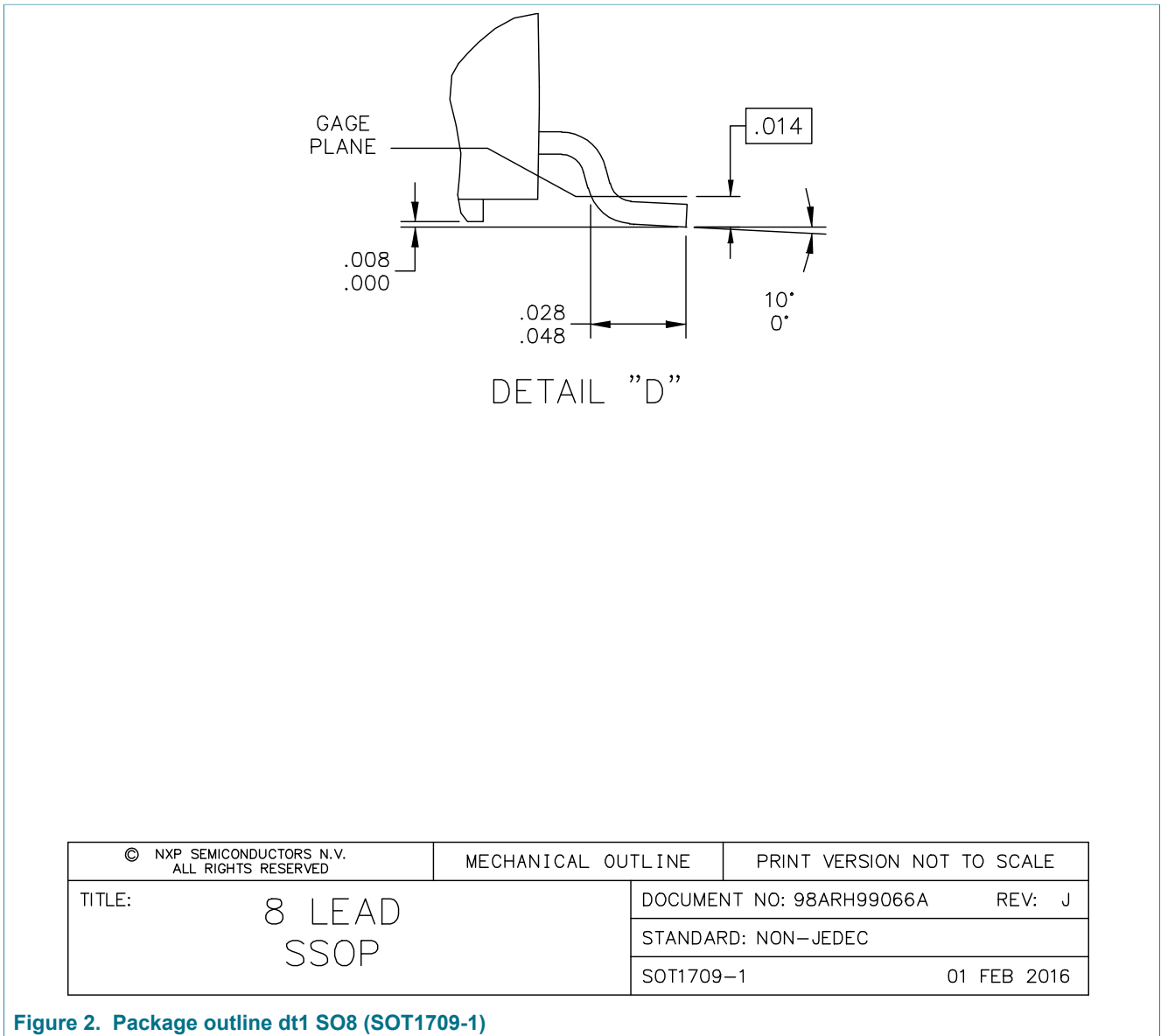


Figure 2. Package outline dt1 SO8 (SOT1709-1)

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NOTES:

1. ALL DIMENSIONS IN INCHES.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.  
MOLD FLASH OR PROTRUSION SHALL NOT EXCEED .006 INCHES PER SIDE.
4. ALL VERTICAL SURFACES TO BE 5° MAXIMUM.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.  
ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 INCHES MAXIMUM.

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TITLE: 8 LEAD SSOP	DOCUMENT NO: 98ARH99066A		REV: J
	STANDARD: NON-JEDEC		
	SOT1709-1		01 FEB 2016

Figure 3. Package outline note SO8 (SOT1709-1)

### 3 Legal information

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